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Components and Packaging for Laser Systems V

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Contents

v vii	Authors Conference Committee
	DIODE PACKAGING: JOINT SESSION WITH 10899 AND 10890
10899 04	Three-dimensional steady-state thermal model of a high power diode laser [10899-3]
10899 05	Thermal modelling of laser diode packages [10899-4]
	LASER DIODE PACKAGING I
10899 06	Single mode 500 mW at 633 nm using all semiconductor master oscillator and a dual stage amplifier [10899-5]
10899 08	The application of telecoms-style packaging techniques to narrow linewidth laser modules for quantum technologies [10899-7]
10899 09	Intelligent simultaneous active sub-micron multi-component alignment for next generation datacom applications [10899-8]
10899 0A	Development of high power annular diode laser array using hard solder [10899-9]
	LASER DIODE PACKAGING II
10899 OC	Fused silica fast axis collimator lens for blue high-power laser diodes [10899-11]
10899 0D	Design and realization of future compact external-cavity diode laser systems [10899-12]
	ADVANCED LASER PACKAGING SOLUTIONS
10899 OF	Integrated photonics for NASA applications (Invited Paper) [10899-14]
10899 OH	Spaceflight 100W, 1940nm polarization maintaining Tm doped fiber laser for pumping Q-switched 2µm Ho:YLF [10899-16]

	HIGH POWER/ENERGY LASER COMPONENTS AND PACKAGING I
10899 OQ	Impact of angular pump power distribution on double-clad fiber temperature and incidence on high-power fiber laser reliability [10899-25]
10899 OS	A simple technique for direct, high power laser beam profile measurement using thermal imagers [10899-27]
	HIGH POWER/ENERGY LASER COMPONENTS AND PACKAGING II
10899 OT	New self-starting mode locked laser with active phase control (Invited Paper) [10899-28]
	HIGH POWER/ENERGY LASER COMPONENTS AND PACKAGING III
10899 10	Spectral and concentration dependence of the Verdet coefficient of dysprosium doped germanate glass [10899-35]
<u> </u>	EMERGING LASER COMPONENTS
10899 13	KYW crystal as a new material for acousto-optic Q-switches [10899-38]
	POSTER SESSION
10899 17	Irradiation test of graphene saturable absorber in mode-locked Er-fiber laser [10899-42]
10899 19	High-index-contrast Bragg gratings fabricated in fluoride fiber with 513-nm femtosecond laser [10899-44]
10899 1A	High efficiency mode field adapters fabricated with CO ₂ laser splicer [10899-45]